

Title (en)

Method of manufacture of a multichip module using bump contacts

Title (de)

Verfahren zur Herstellung eines Multichipmoduls mittels Kontakthöcker

Title (fr)

Procédé pour la fabrication d'une module multipuce avec des électrodes à protubérance

Publication

**EP 0581152 B1 19971015 (DE)**

Application

**EP 93111497 A 19930717**

Priority

DE 4225138 A 19920730

Abstract (en)

[origin: EP0581152A2] The invention relates to making contact to multichip modules. Contact is made to the individual chips of the multichip module by the flip-chip technique. Contact bumps are deposited on a substrate and the chips are mounted on the contact bumps so that the contact areas of the individual ICs of the chips are connected to the contact bumps of the substrate by cold welding.

IPC 1-7

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IPC 8 full level

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CPC (source: EP)

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Cited by

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